Materials of Engineering ENGR 151

CORROSION ELECTRICAL PROPERTIES

### GALVANIC SERIES

### Ranking of the reactivity of metals/alloys in seawater

more cathodic (inert)

more anodic (active) Platinum Gold Graphite Titanium Silver 316 Stainless Steel (passive) Nickel (passive) Copper Nickel (active) Tin Lead 316 Stainless Steel (active) Iron/Steel **Aluminum Alloys** Cadmium Zinc Magnesium

Table 17.2, *Callister & Rethwisch 9e*. Source is M.G. Fontana, *Corrosion Engineering*, 3rd ed., McGraw-Hill Book Company, 1986. Reprinted with permission)

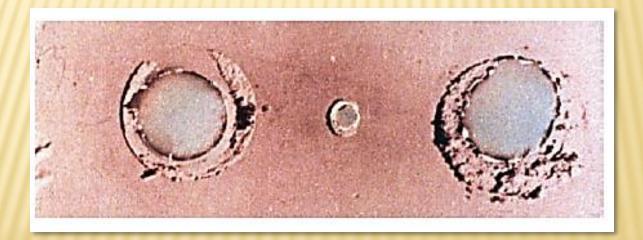
- Uniform Attack: Occurs with equal intensity over the entire exposed surface
  - Often leaves behind a scale or residue
  - E.g. Rusting of steel and iron, tarnishing of silverware
- Galvanic Corrosion: Occurs when two metals or alloys having different compositions are electrically coupled when exposed to electrolyte
  - Constitutes an electrochemical cell
  - More reactive metal experiences corrosion
  - Seawater is a medium that is conducive to galvanic corrosion

### **Example of Galvanic Corrosion**

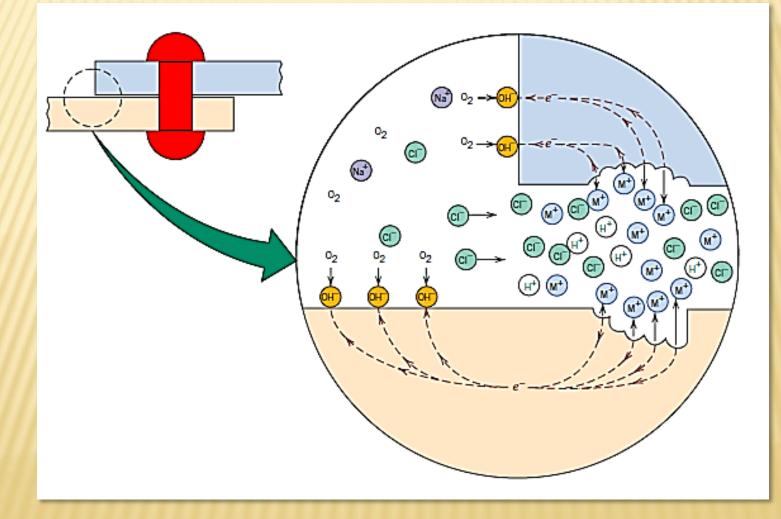


Magnesium shell

- **Crevice Corrosion:** May occur as a consequence of concentration differences of ions or dissolved gases in the electrolyte solution
  - Crevices are areas where concentration may drop, conducive to corrosion – crevice corrosion



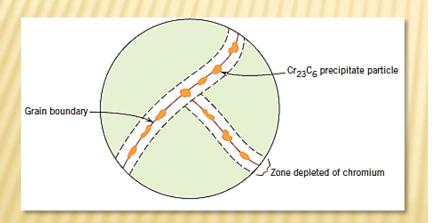
### **Crevice Corrosion – Schematic**

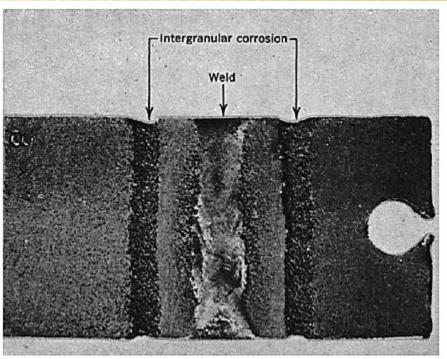


- **Pitting Corrosion:** Localized corrosion attack involving the formation of small pits or holes
  - Top-down direction, nearly vertical
  - Insidious, may go undetected till failure occurs
  - Similar mechanism to crevice corrosion



- Intergranular Corrosion: Occurs along grain boundaries
  - Macroscopic specimen disintegrates along grain boundaries
  - Prevalent in some stainless steels



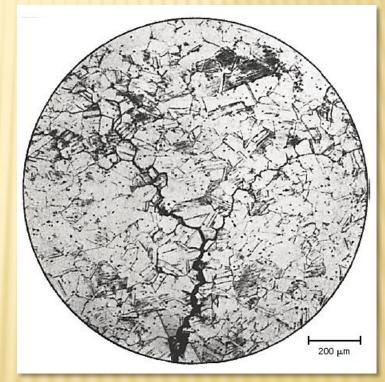


- Selective Leaching: Found in solid solution alloys when one constituent is preferentially removed as a result of corrosion processes
  - E.g. Dezincification of brass
    - Zinc is selectively leached from a copper-zinc brass alloy
    - Properties of alloy adversely affected
  - May also occur in other alloys in which aluminum, iron, cobalt, chromium and other elements are vulnerable to preferential removal

- Stress Corrosion: Also known as corrosion cracking – combined action of a tensile stress and a corrosive environment
  - Some materials which are virtually inert in a particular corrosive environment become susceptible to corrosion when a stress is applied
  - Small cracks form and propagate in a direction perpendicular to the stress

#### **Stress Corrosion – Examples**





Along grain boundaries

- Hydrogen Embrittlement: Significant reduction in ductility and tensile strength when atomic hydrogen penetrates into the material
  - Seen in various metal alloys and some steels
  - Atomic hydrogen (H) diffuses interstitially through the crystal lattice, causing cracking

#### Stress corrosion

• Uniform Attack Oxidation & reduction reactions occur uniformly over surfaces.

- Selective Leaching Preferred corrosion of one element/constituent [e.g., Zn from brass (Cu-Zn)].
  - Intergranular

Corrosion along grain boundaries, often where precip. particles form.

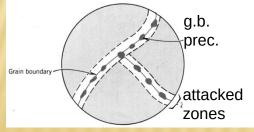
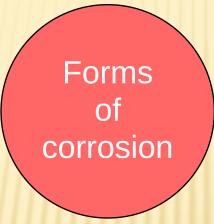


Fig. 17.18, Callister & Rethwisch 9e.

Corrosion at crack tips when a tensile stress is present.



• Galvanic

Dissimilar metals are physically joined in the presence of an electrolyte. The more anodic metal corrodes.

#### Erosion-corrosion

Combined chemical attack and mechanical wear (e.g., pipe elbows).

#### • Pitting

Downward propagation of small pits and holes.



Fig. 17.17, *Callister & Rethwisch 9e*. (From M.G. Fontana, *Corrosion Engineering*, 3rd ed., McGraw-Hill Book Company, 1986.)

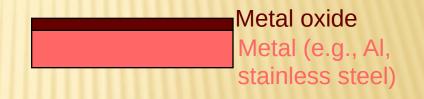
• Crevice Narrow and confined spaces.



Fig. 17.15, *Callister & Rethwisch 9e*. (Courtesy LaQue Center for Corrosion Technology, Inc.)

# CORROSION PREVENTION (I)

- Materials Selection
  - -- Use metals that are relatively unreactive in the corrosion environment -- e.g., Ni in basic solutions
  - -- Use metals that passivate
    - These metals form a thin, adhering oxide layer that slows corrosion.

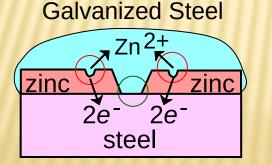


- Lower the temperature (reduces rates of oxidation and reduction)
- Apply physical barriers -- e.g., films and coatings

## CORROSION PREVENTION (II)

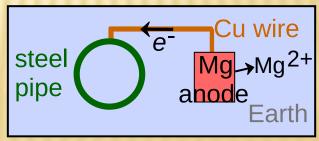
- Add inhibitors (substances added to solution that decrease its reactivity)
  - -- Slow oxidation/reduction reactions by removing reactants (e.g., remove O<sub>2</sub> gas by reacting it w/an inhibitor).
  - -- Slow oxidation reaction by attaching species to the surface.
- Cathodic (or sacrificial) protection
  - -- Attach a more anodic material to the one to be protected.





e.g., zinc-coated nail

Using a sacrificial anode

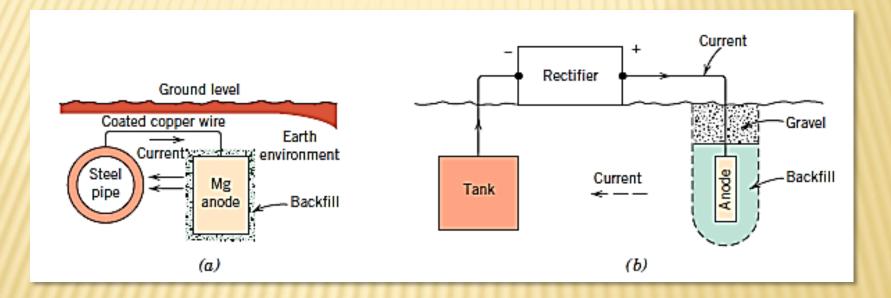


e.g., Mg Anode

Adapted from Fig. 17.23(a), *Callister & Rethwisch* 9e.

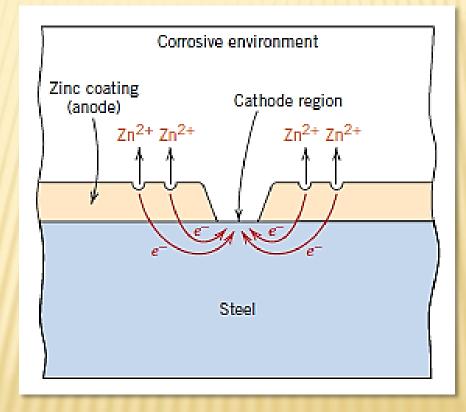
## CORROSION PREVENTION (III)

Cathodic (or sacrificial) protection



# CORROSION PREVENTION (IV)

#### **Galvanic** protection



## SUMMARY

- Metallic corrosion involves electrochemical reactions
  -- electrons are given up by metals in an oxidation reaction
  -- these electrons are consumed in a reduction reaction
- Metals and alloys are ranked according to their corrosiveness in standard emf and galvanic series.
- Temperature and solution composition affect corrosion rates.
- Forms of corrosion are classified according to mechanism
- Corrosion may be prevented or controlled by:
  - -- materials selection
  - -- reducing the temperature
  - -- applying physical barriers
  - -- adding inhibitors
  - -- cathodic protection

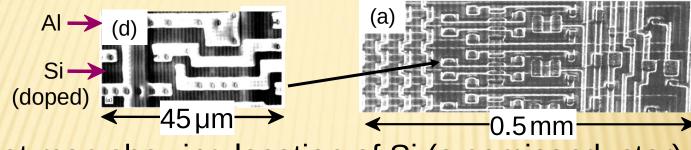
## CHAPTER 18: ELECTRICAL PROPERTIES

### **ISSUES TO ADDRESS...**

- How are electrical conductance and resistance characterized?
- What are the physical phenomena that distinguish conductors, semiconductors, and insulators?
- For metals, how is conductivity affected by imperfections, temperature, and deformation?
- For semiconductors, how is conductivity affected by impurities (doping) and temperature?

## VIEW OF AN INTEGRATED CIRCUIT

Scanning electron micrographs of an IC:



A dot map showing location of Si (a semiconductor):
 -- Si shows up as light regions.

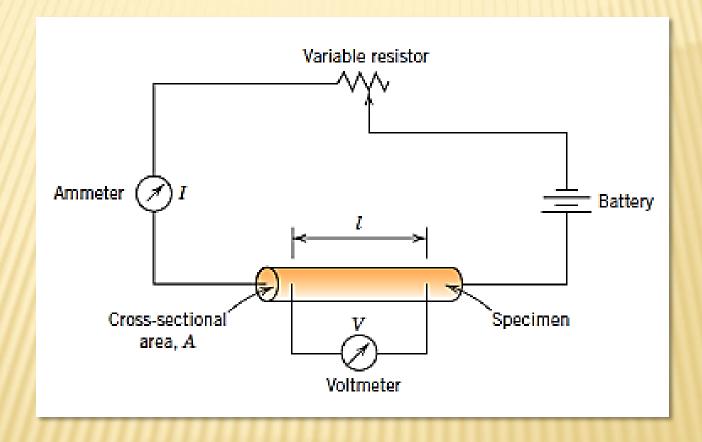
A dot map showing location of Al (a conductor):
 Al shows up as light regions.

Fig. (d) from Fig. 12.27 (a), *Callister & Rethwisch 3e*. (Courtesy Nick Gonzales, National Semiconductor Corp., West Jordan, UT.)



Figs. (a), (b), (c) from Fig. 18.27, *Callister & Rethwisch 9e.* 

## ELECTRICAL CONDUCTION

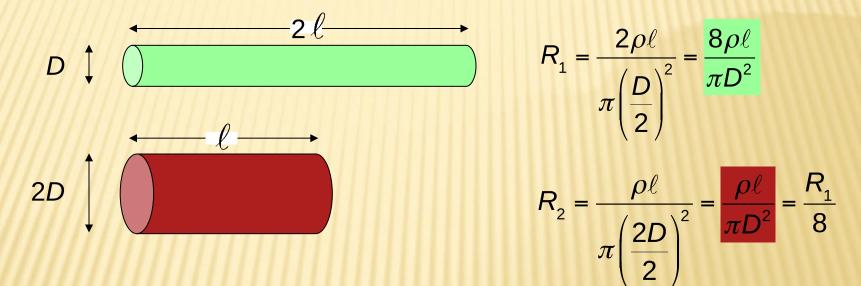


### ELECTRICAL CONDUCTION

- Ohm's Law:
  voltage drop (volts = J/C)
  C = Coulomb
  V = I R resistance (Ohms) current (amps = C/s)
- Resistivity, *ρ*:
  - -- a material property that is independent of sample size and geometry RA of current flow
  - Conductivity,  $\sigma$   $\rho = \frac{1}{\rho}$  $\sigma = \frac{1}{\rho}$

### ELECTRICAL PROPERTIES

× Which will have the greater resistance?



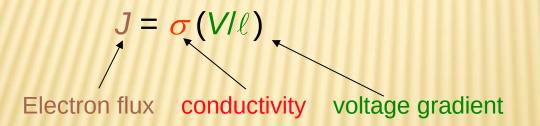
- × Analogous to flow of water in a pipe
- Resistance depends on sample geometry and size.

## REFINITIONS

### **Further definitions**

$J = \sigma E$	<= anothei	r way to sta	ite Ohr	m's law
$J \equiv \text{current de}$	ensity =	current surface area	$\frac{I}{A} = \frac{I}{A}$	like a flux

E = electric field potential =  $V/\ell$ 



### CONDUCTIVITY: COMPARISON

• Room temperature values  $(Ohm-m)^{-1} = (\Omega - m)^{-1}$ 

METALS	conductors
Silver	6.8 x 10 <sup>7</sup>
Copper	6.0 x 10 <sup>7</sup>
Iron	1.0 x 10 <sup>7</sup>

CERAMICSSoda-lime glass $10^{-10}$ - $10^{-11}$ Concrete $10^{-9}$ Aluminum oxide $<10^{-13}$ 

SEMICONDUCTORSSilicon $4 \times 10^{-4}$ Germanium $2 \times 10^{0}$ GaAs $10^{-6}$ 

POLYMERS Polystyrene Polyethylene

<10<sup>-14</sup> 10<sup>-15</sup>-10<sup>-17</sup>

insulators

#### semiconductors

Selected values from Tables 18.1, 18.3, and 18.4, Callister & Rethwisch 9e.

## EXAMPLE: CONDUCTIVITY PROBLEM

What is the minimum diameter (D) of the wire so that V < 1.5 V?

